

METEOR PRIMER W

SOLVENT-FREE EPOXY RESIN FILLED PRIMER

USE

For making priming and base layers (for aggregate backfill). For making compounds Putties for various applications depending on the micro fillers used. For making layers Leveling layers. For use as part of a system of horizontal repair of concrete surfaces as a bonding layer - as a result of its use with the "wet-on-wet" method, a permanent bonding of concrete layers is obtained.

SUBSTRATE

The mineral substrate should be of class min. C20/25, with a stripping strength of min. 1.5 MPa. During curing, the resin is not sensitive to moisture, either from the substrate or from the air, however, the surface moisture of the substrate should not exceed 15% (substrate should be dull damp, e.g. surface dried after flooding with water). Please note that sealing an unsealed substrate with an epoxy system may result in the system becoming detached due to the vapour pressure in the substrate.

ADVANTAGES

- total resistance to crystallisation during storage
- versatile in use
- very good adhesion to substrate
- good penetration depth
- can be backfilled with sand
- very good mechanical properties
- viscosity can be reduced by diluting with epoxy solvents
- colour: silicon

METHODS OF APPLICATION

Depending on the use.

EFFICIENCY

Depending on the use:

- concrete priming: approx. 0,3 kg/m²;
- base layer for sand backfill: 0,6-0,8 kg/m²

MIXING CONDITIONS

Before use, mix Component A, add the weighed amount of Component B, mix thoroughly for approx. 3-4 minutes using a slow speed mixer. Once the components have been mixed, the curing process has begun irreversibly, always prepare a portion that can be applied evenly within approx. 15-20 min. The relative humidity of the air should not exceed 80%.

TECHNICAL PARAMETERS

	PARAMETER	VALUE	UNIT
1	Mixing ratio Component A Component B	100 15	by weight by weight
1	Density	1,45 to 1,85	[g/cm ³]
2	Viscosity	2000 to 3500	[mPa*s]
3	Shelf life at 20°C	20-25	[min]
4	Curing time	24	[h]
5	Reaction to fire	B _{fl} -s1	-
6	Temperature resistance during operation	to 70	°C
7	Water permeability	lack of permeability	-
8	Abrasion resistance	AR1 AR0,5 for the smooth system	-
9	Compressive strength	>80	[MPa]
10	Bending strength	>60	[MPa]
11	Peel strength (primed surface)	>2,5	[MPa]
12	Surface hardness (14 days at 20°C)	min. 80 Shore D	-
13	Impact resistance	≥IR4	-
14	Slip protection	R11 (for parking system on 0.4-0.8 mm aggregate) R9 (for the smooth system)	-

TOOLS CLEANING

Clean tools and any contamination freshly with acetone or other epoxy solvent. If cured, the resin can only be removed mechanically.

CLEANING AND MAINTENANCE OF A RESIN FLOOR

- **Si-Clean** – preparation for daily cleaning and care
- **Si-Wax** – self-gloss polymer paste
- **Si-Active Resin Clean** – alkaline remover for deep cleaning and removal of heavy soiling

STORAGE

Store resin and hardener in closed factory containers. Do not allow to freeze. Do not heat above 25°C.

CONTAINERS

Metal cans (Component A and B).

HEALTH AND SAFETY REQUIREMENTS

Some components of flooring compounds in their uncured state are harmful to health. They can cause allergies in particularly sensitive people. Special precautions must be taken when carrying out the work. The rooms where the floors are prepared and applied must be well ventilated. Workers should wear: clothing, shoes, protective goggles and gloves. Detailed safety rules are given in the Safety Data Sheets of the ingredients. METEOR PRIMER W epoxy flooring compounds, after curing, are physiologically inert for the human body, provide a washable surface, and therefore can be used in the pharmaceutical, cosmetic and food industries.

Note: The above information has been compiled to the best of our technical knowledge, but is not legally binding.

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